

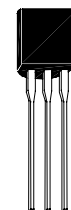


HSD468

NPN Epitaxial Planar Transistor

Description

The HSD468 is designed for general purpose low frequency power amplifier applications.



TO-92

Absolute Maximum Ratings

- Maximum Temperatures
 - Storage Temperature -55 ~ +150 °C
 - Junction Temperature 150 °C Maximum
- Maximum Power Dissipation
 - Total Power Dissipation ($T_A=25^{\circ}\text{C}$) 900 mW
- Maximum Voltages and Currents ($T_A=25^{\circ}\text{C}$)
 - V_{CBO} Collector to Base Voltage 25 V
 - V_{CEO} Collector to Emitter Voltage 20 V
 - V_{EBO} Emitter to Base Voltage 5 V
 - I_C Collector Current 1 A

Electrical Characteristics ($T_A=25^{\circ}\text{C}$)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BV_{CBO}	25	-	-	V	$I_C=10\mu\text{A}$, $I_E=0$
BV_{CEO}	20	-	-	V	$I_C=1\text{mA}$, $I_B=0$
BV_{EBO}	5	-	-	V	$I_E=10\mu\text{A}$, $I_C=0$
I_{CBO}	-	-	1	μA	$V_{CB}=20\text{V}$, $I_E=0$
$^*V_{CE(sat)}$	-	-	500	mV	$I_C=0.8\text{A}$, $I_B=80\text{mA}$
$V_{BE(on)}$	-	-	1	V	$V_{CE}=2\text{V}$, $I_C=500\text{mA}$
$^*h_{FE}$	120	-	240		$V_{CE}=2\text{V}$, $I_C=500\text{mA}$
f_T	-	190	-	MHz	$V_{CE}=2\text{V}$, $I_C=500\text{mA}$
Cob	-	22	-	pF	$V_{CB}=10\text{V}$, $f=1\text{MHz}$, $I_E=0$

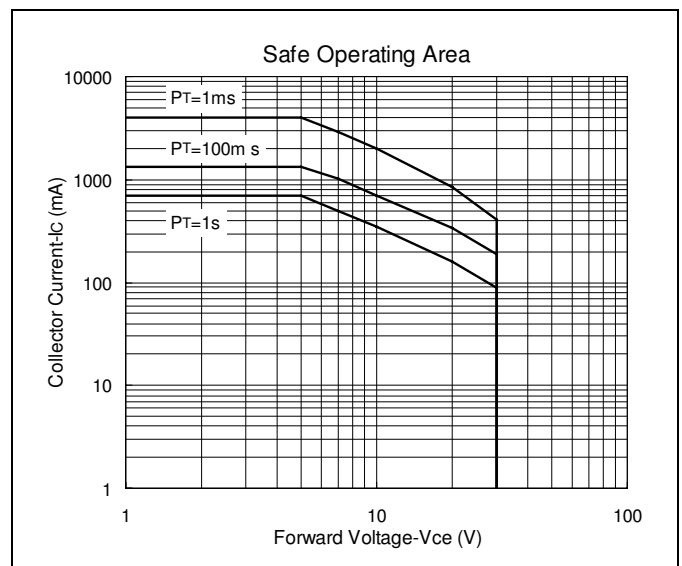
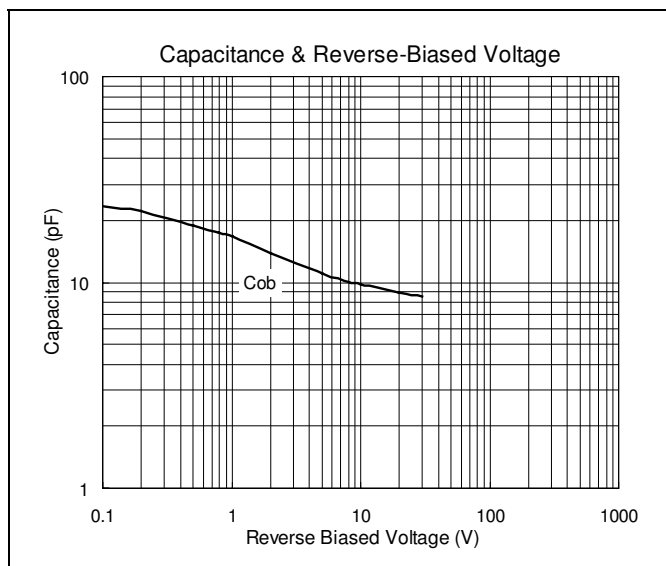
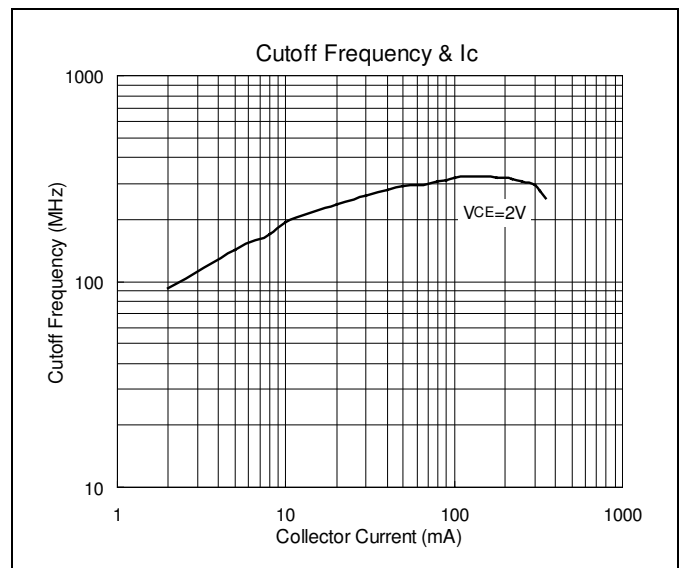
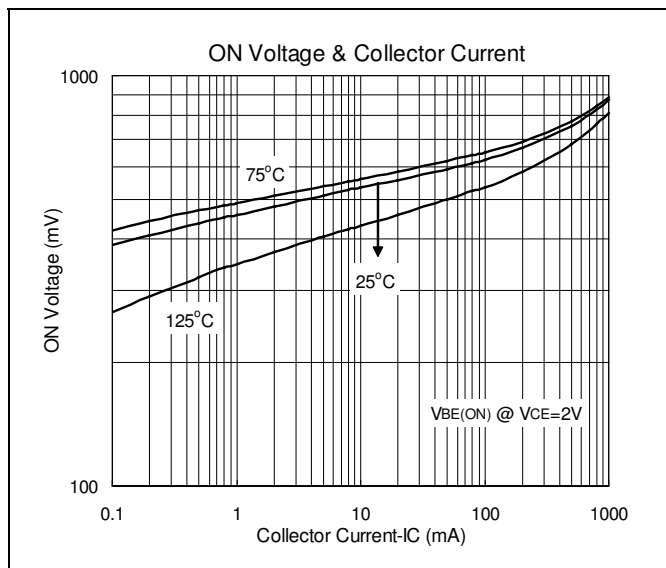
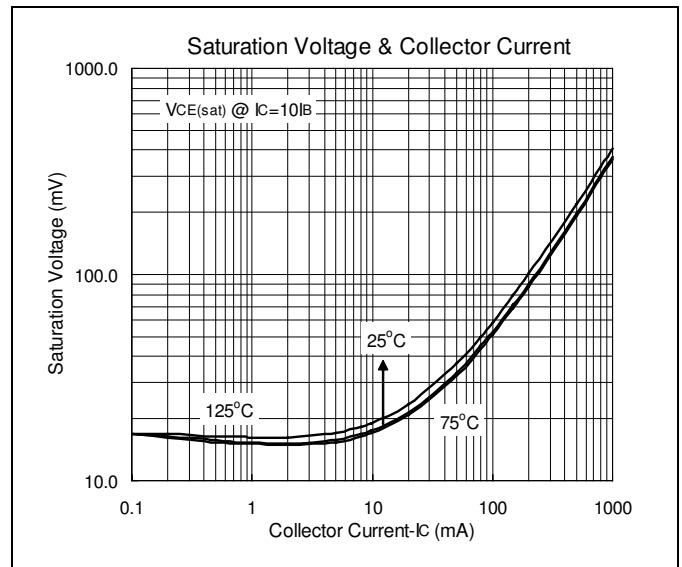
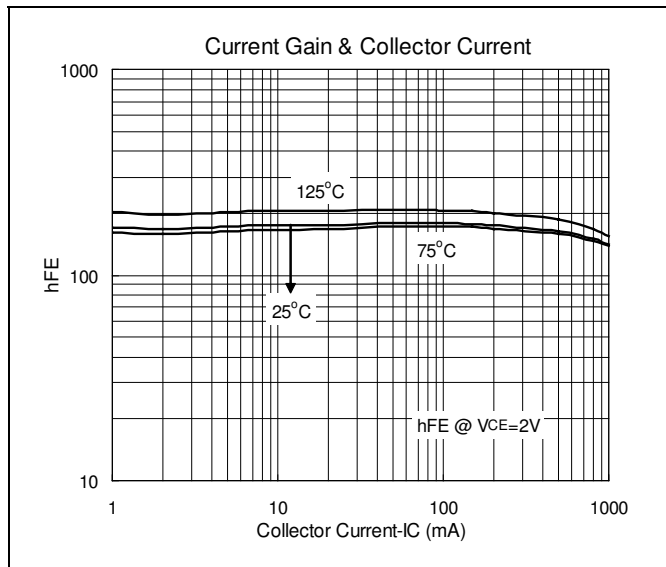
*Pulse Test: Pulse Width $\leq 380\mu\text{s}$, Duty Cycle $\leq 2\%$

Classification of h_{FE}

Rank	C
Range	120-240

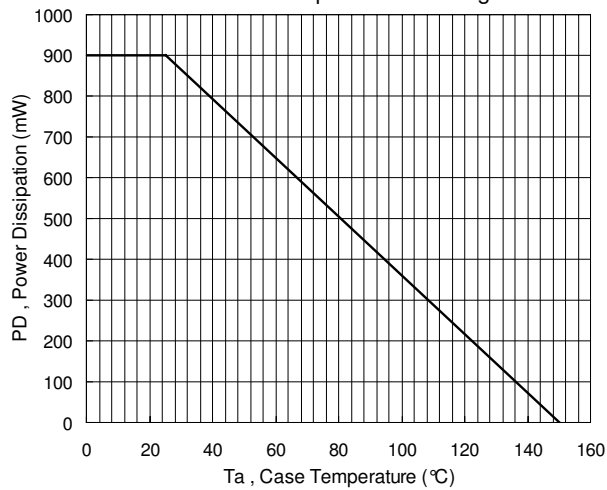


Characteristics Curve

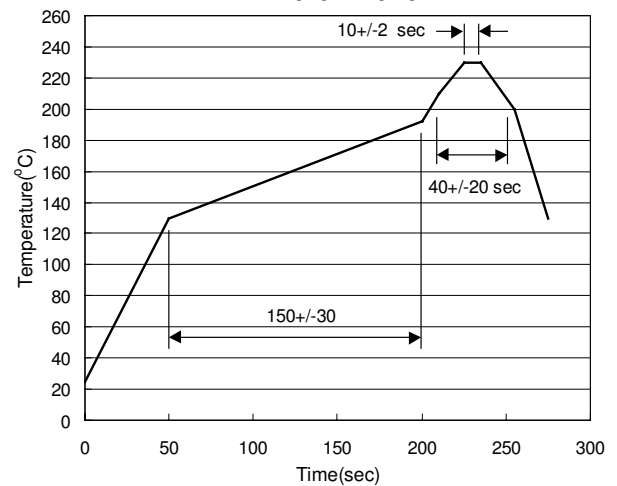




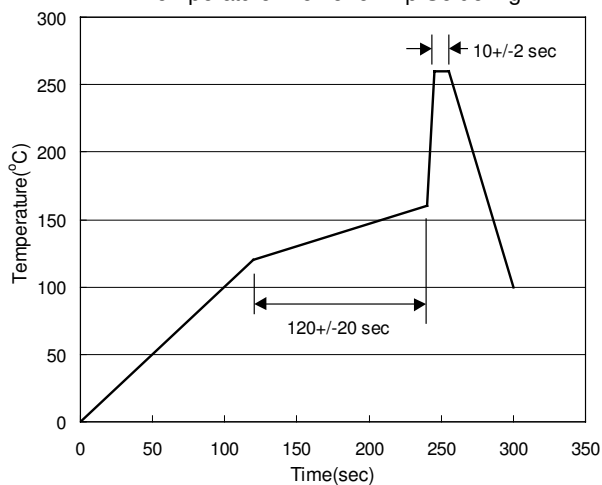
Power Temperature Derating



IR Reflow Profile

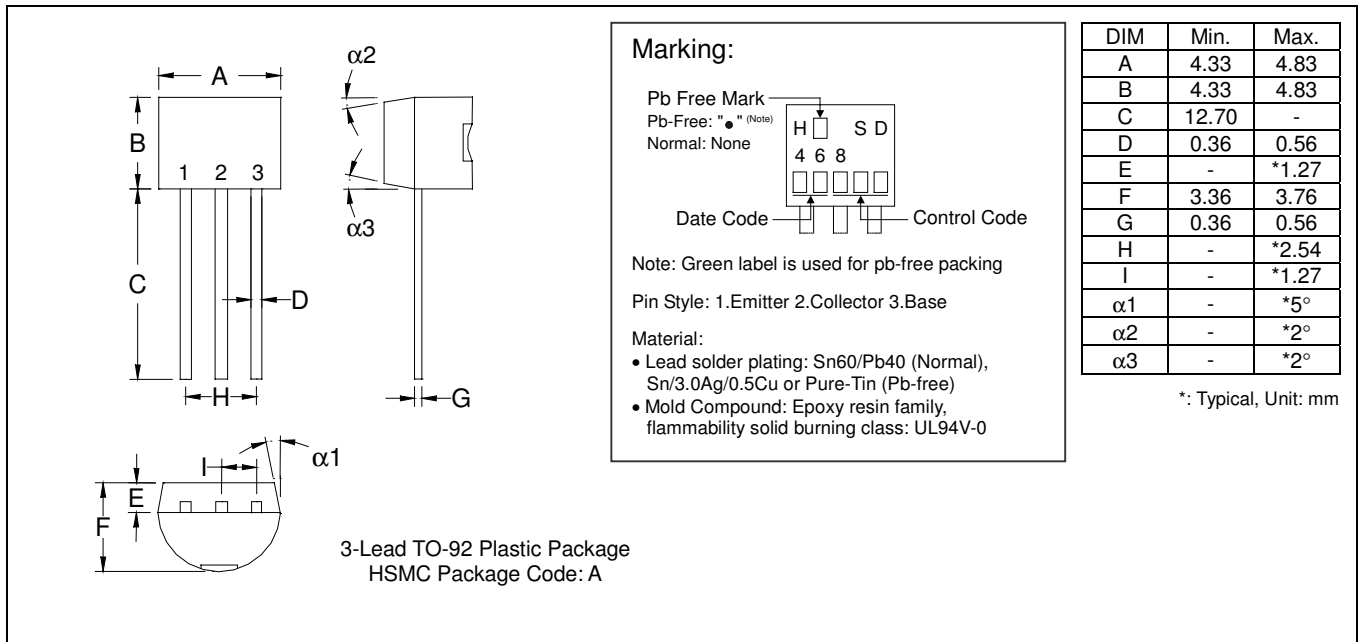


Temperature Profile for Dip Soldering

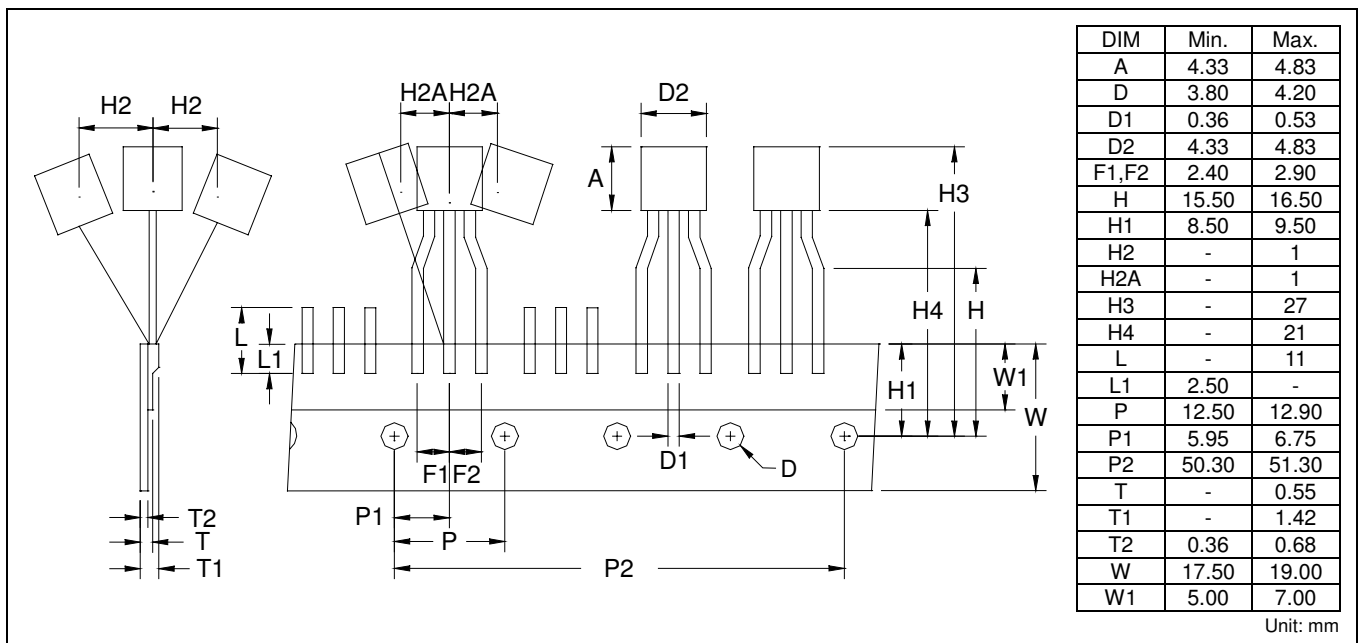




TO-92 Dimension



TO-92 Taping Dimension



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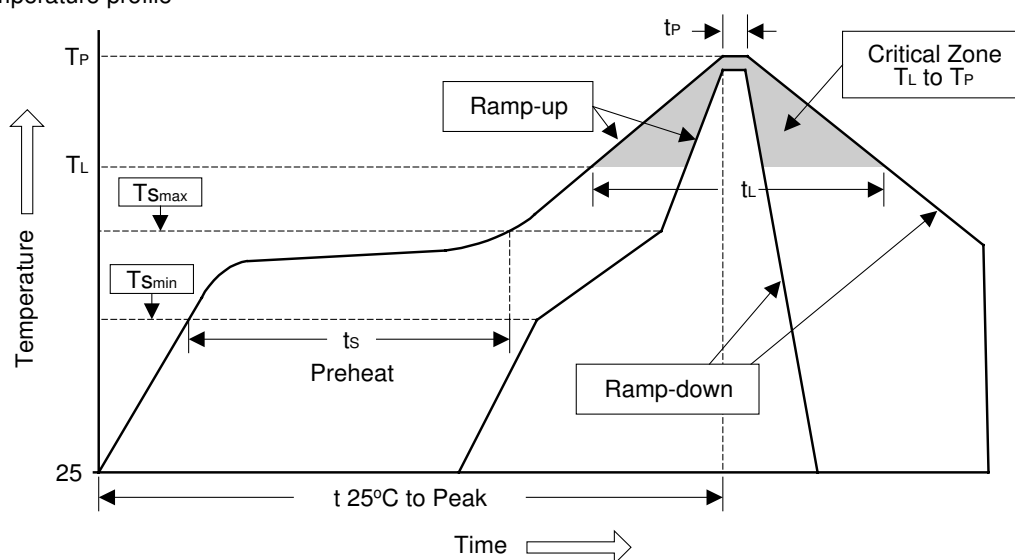
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Soldering Methods for HSMC's Products

1. Storage environment: Temperature=10°C~35°C Humidity=65%±15%
2. Reflow soldering of surface-mount devices

Figure 1: Temperature profile



Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average ramp-up rate (T_L to T_P)	<3°C/sec	<3°C/sec
Preheat		
- Temperature Min (T_{smin})	100°C	150°C
- Temperature Max (T_{smax})	150°C	200°C
- Time (min to max) (t_s)	60~120 sec	60~180 sec
T_{smax} to T_L		
- Ramp-up Rate	<3°C/sec	<3°C/sec
Time maintained above:		
- Temperature (T_L)	183°C	217°C
- Time (t_L)	60~150 sec	60~150 sec
Peak Temperature (T_P)	240°C +0/-5°C	260°C +0/-5°C
Time within 5°C of actual Peak Temperature (t_p)	10~30 sec	20~40 sec
Ramp-down Rate	<6°C/sec	<6°C/sec
Time 25°C to Peak Temperature	<6 minutes	<8 minutes

3. Flow (wave) soldering (solder dipping)

Products	Peak temperature	Dipping time
Pb devices.	245°C ±5°C	10sec ±1sec
Pb-Free devices.	260°C ±5°C	10sec ±1sec